

## FEATURES

- | 150 Watts Peak Pulse Power per Line(tp=8/20s)
- | Protects one bidirectional I/O line
- | Low clamping voltage
- | Working voltages : 3.3 V
- | Low leakage current

## APPLICATIONS

- | Cell Phone Handsets and Accessories
- | Microprocessor based equipment
- | Personal Digital Assistants (PDA' s)
- | Notebooks, Desktops, and Servers
- | Portable Instrumentation
- | Peripherals
- | Pagers



SOD-523



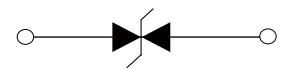
Marking

## IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

## APPROVALS

- RoHS** | Compliance with 2011/65/EU
- HF** | Compliance with IEC61249-2-21:2003



Schematic Symbol

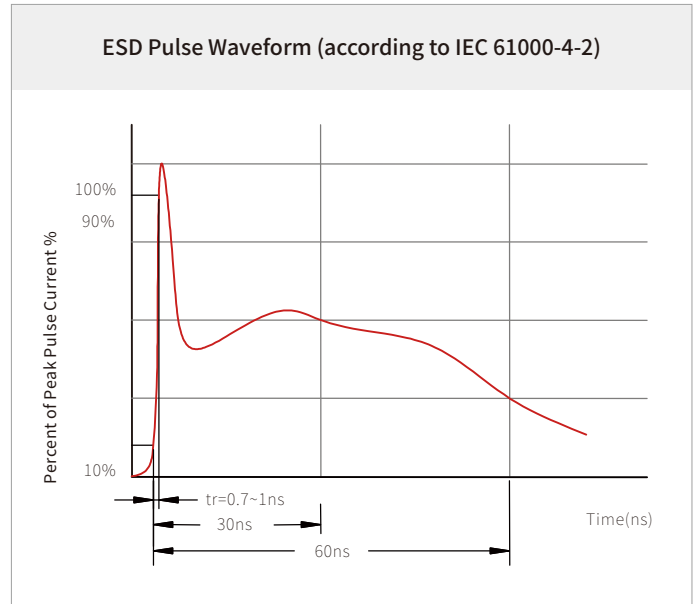
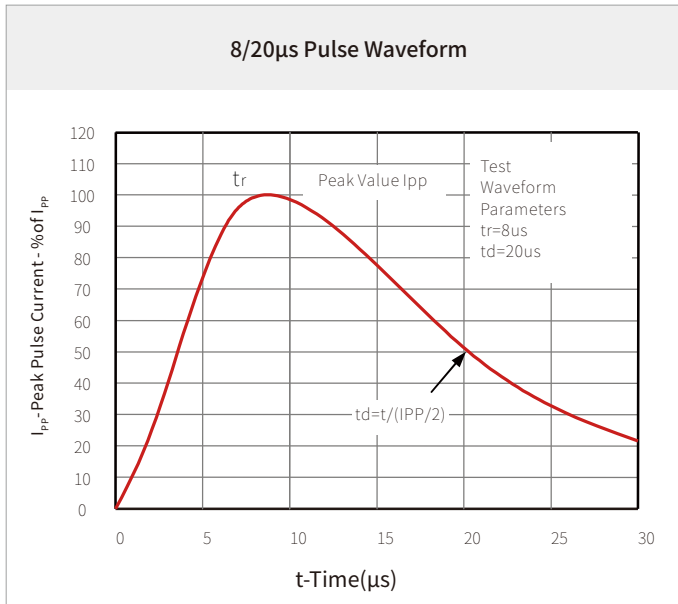
## THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
$P_{PP}$	Peak Pulse Power (tp=8/20μs waveform)	150	Watts
$T_J$	Operating Temperature Range	-55 to +125	°C
$T_{STG}$	Storage Temperature Range	-55 to +150	°C

## ELECTRICAL CHARACTERISTICS

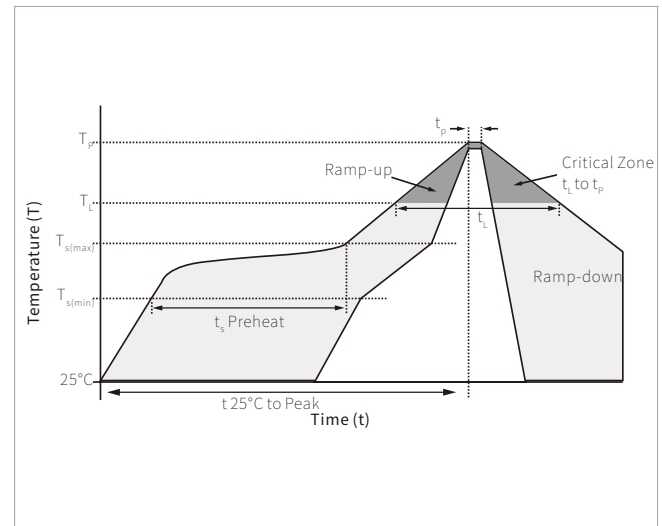
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$V_{RWM}$	Reverse Stand-off Voltage				3.3	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T=1mA$	3.5	5.5		V
$I_R$	Reverse Leakage Current	$V_{RWM}=3.3V$			1	μA
$V_C$	Clamping Voltage	$I_{PP}=8A, tp=8/20us$			15	V
$I_{PP}$	Peak Pulse Current	tp=8/20us			8	A
$C_J$	Off State Junction Capacitance	$V_R=0V, f=1MHz$			15	pF

## CHARACTERISTIC CURVES

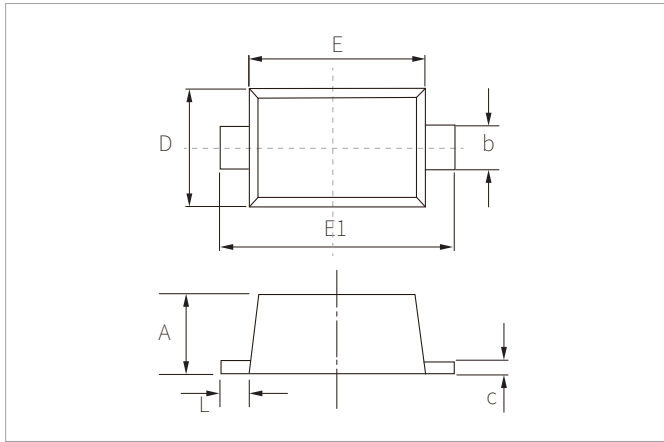


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

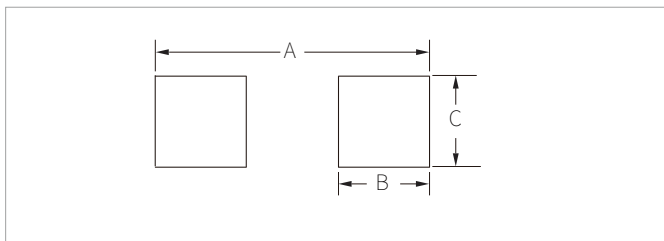


## SOD-523 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.80	0.020	0.031
b	0.25	0.35	0.010	0.014
c	0.07	0.20	0.003	0.008
D	0.70	0.90	0.028	0.035
E	1.10	1.30	0.043	0.051
E1	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Min.	Min.	Min.
A	2.00		0.0787	
B	0.60		0.0236	
C	0.70		0.0276	

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE5D15B3.3A	SOD-523	3000PCS	7"

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